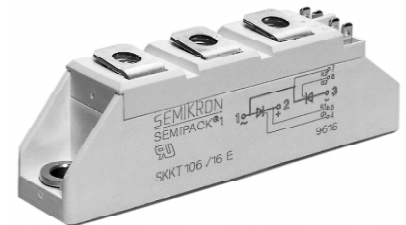


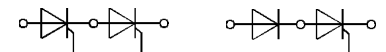
V _{RSM}	V _{RRM}	(dv/dt) _{cr}	I _{T(RMS)} (maximum value for continuous operation)			
			50 A			
V	V	V/μs	I _{T(AV)} (sin. 180; T _{case} = 68 °C)			
			32 A			
500	400	500	–	–	SKKH 26/04 D	–
700	600	500	SKKT 26/06 D	–	SKKH 26/06 D	SKKH 27/06 D
900	800	500	SKKT 26/08 D	SKKT 27/08 D ¹⁾	SKKH 26/08 D	SKKH 27/08 D
1300	1200	1000	SKKT 26/12 E	SKKT 27/12 E ¹⁾	SKKH 26/12 E	SKKH 27/12 E
1500	1400	1000	SKKT 26/14 E	SKKT 27/14 E ¹⁾	SKKH 26/14 E	SKKH 27/14 E
1700	1600	1000	SKKT 26/16 E	SKKT 27/16 E ¹⁾	SKKH 26/16 E	SKKH 27/16 E

SEMIPACK® 1 Thyristor / Diode Modules

SKKT 26 **SKKH 26**
SKKT 27 **SKKH 27**
SKKT 27B



Symbol	Conditions	SKKT 26 SKKH 26	SKKT 27 SKKT 27B SKKH 27	Units
I _{T(AV)}	sin. 180; T _{case} = 68 °C	32		A
I _D	T _{case} = 85 °C	25		A
	B2/B6	T _{amb} = 45 °C; P 3/180	38 / 50	A
I _{RMS}	T _{amb} = 35 °C; P 3/180 F	60 / 77		A
	W1/W3	T _{amb} = 45 °C; P 3/180	52 / 3 x 37	A
I _{TSM}	T _{vj} = 25 °C; 10 ms	550		A
i ² t	T _{vj} = 125 °C; 10 ms	480		A
	T _{vj} = 25 °C; 8,3 ... 10 ms	1 500		A ² s
t _{gd}	T _{vj} = 125 °C; 8,3 ... 10 ms	1 150		A ² s
	T _{vj} = 25 °C; I _G = 1 A	1		μs
t _{gr}	d _{IG} /dt = 1 A/μs	1		μs
(di/dt) _{cr}	V _D = 0,67 · V _{DRM}	150		A/μs
t _q	T _{vj} = 125 °C	typ. 80		μs
I _H	T _{vj} = 25 °C; typ./max.	100 / 200		mA
I _L	T _{vj} = 25 °C; R _G = 33 Ω; typ./max.	250 / 400		mA
V _T	T _{vj} = 25 °C; I _T = 75 A	max. 1,8		V
V _{T(TO)}	T _{vj} = 125 °C	0,9		V
r _T	T _{vj} = 125 °C	12		mΩ
I _{DD} ; I _{RD}	T _{vj} = 125 °C; V _{RD} = V _{RRM} V _{DD} = V _{DRM}	max. 10		mA
V _{GT}	T _{vj} = 25 °C; d.c.	3		V
I _{GT}	T _{vj} = 25 °C; d.c.	150		mA
V _{GD}	T _{vj} = 125 °C; d.c.	0,25		V
I _{GD}	T _{vj} = 125 °C; d.c.	5		mA
R _{thjc}	cont.	0,9 / 0,45		°C/W
R _{thch}	sin. 180	0,95 / 0,48		°C/W
	rec. 120	1,0 / 0,5		°C/W
T _{vj}	} per thyristor / per module	0,2 / 0,1		°C/W
T _{stg}		– 40 ... + 125		°C
V _{isol}		– 40 ... + 125		°C
M ₁	a. c. 50 Hz; r.m.s.; 1 s/1 min	3600 / 3000		V~
M ₂	to heatsink	5 (44 lb. in.) ± 15 % ²⁾		Nm
a	to terminals	3 (26 lb. in.) ± 15 %		Nm
w	approx.	5 · 9,81		m/s ²
		95		g
Case	→ page B 1 – 95	SKKT 26: A 5 SKKH 26: A 6	SKKT 27: A 46 SKKT 27B: A 48 SKKH 27: A 47	



SKKT 26

SKKH 26



**SKKT 27
SKKT 27B**

SKKH 27

Features

- Heat transfer through aluminium oxide ceramic isolated metal baseplate
- Hard soldered joints for high reliability
- UL recognized, file no. E 63 532

Typical Applications

- DC motor control (e.g. for machine tools)
- AC motor soft starters
- Temperature control (e.g. for ovens, chemical processes)
- Professional light dimming (studios, theaters)

¹⁾ Also available in SKKT 27B configuration (case A 48)

²⁾ See the assembly instructions

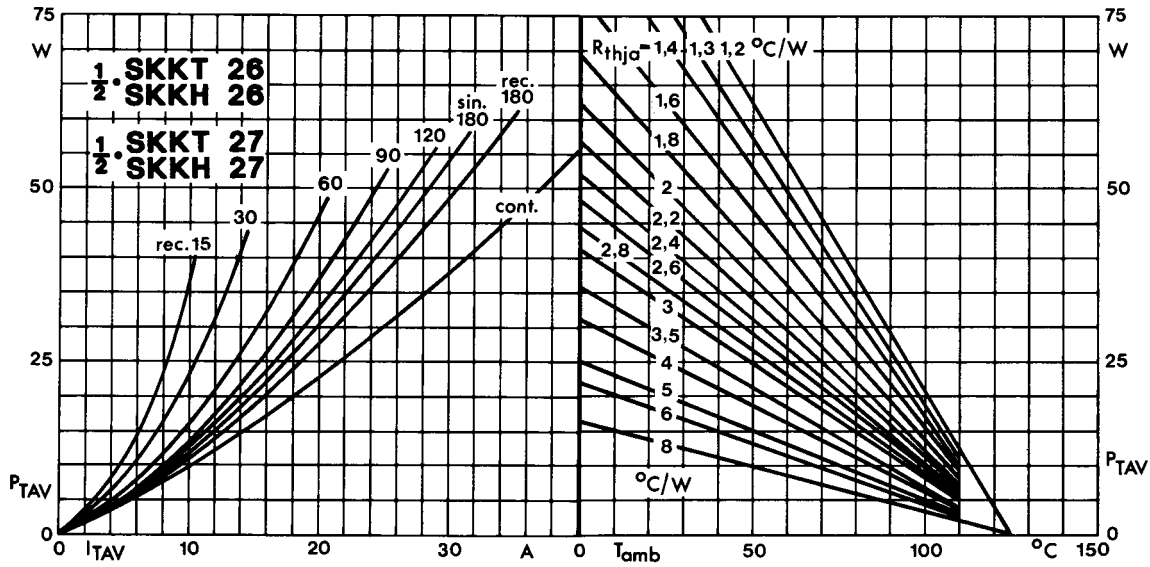


Fig. 1 Power dissipation per thyristor vs. on-state current and ambient temperature

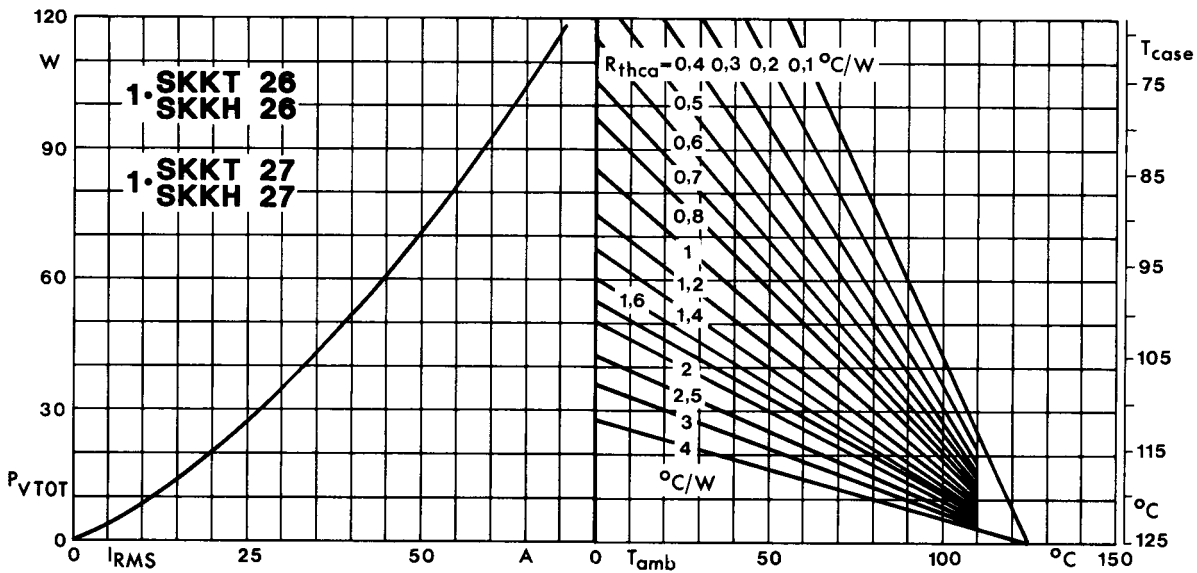


Fig. 2 Power dissipation per module vs. rms current and case temperature

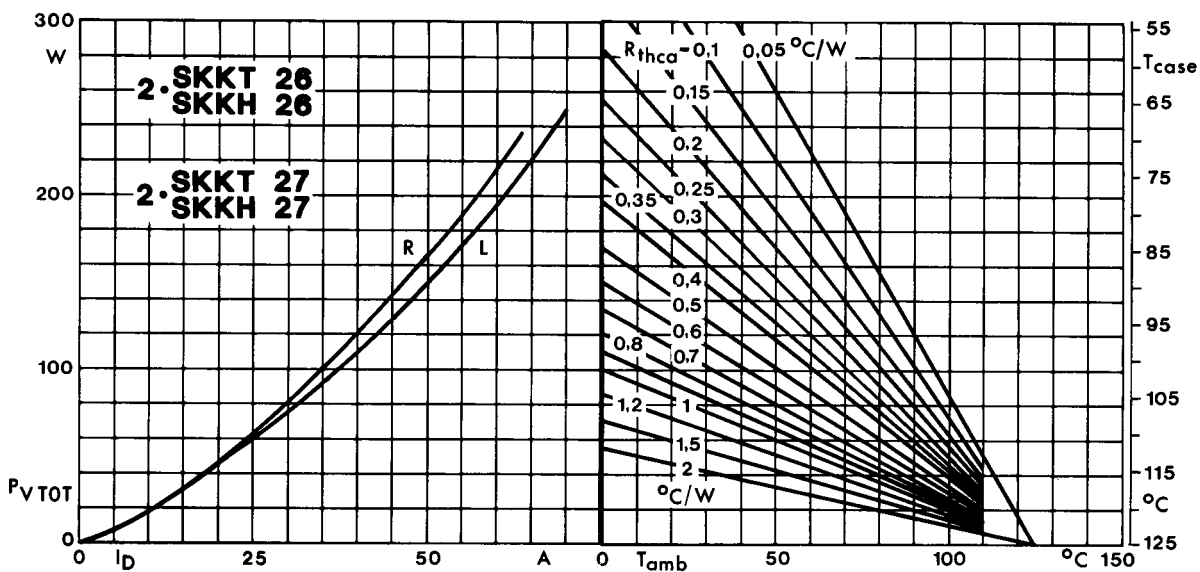


Fig. 3 Power dissipation of two modules vs. direct current and case temperature

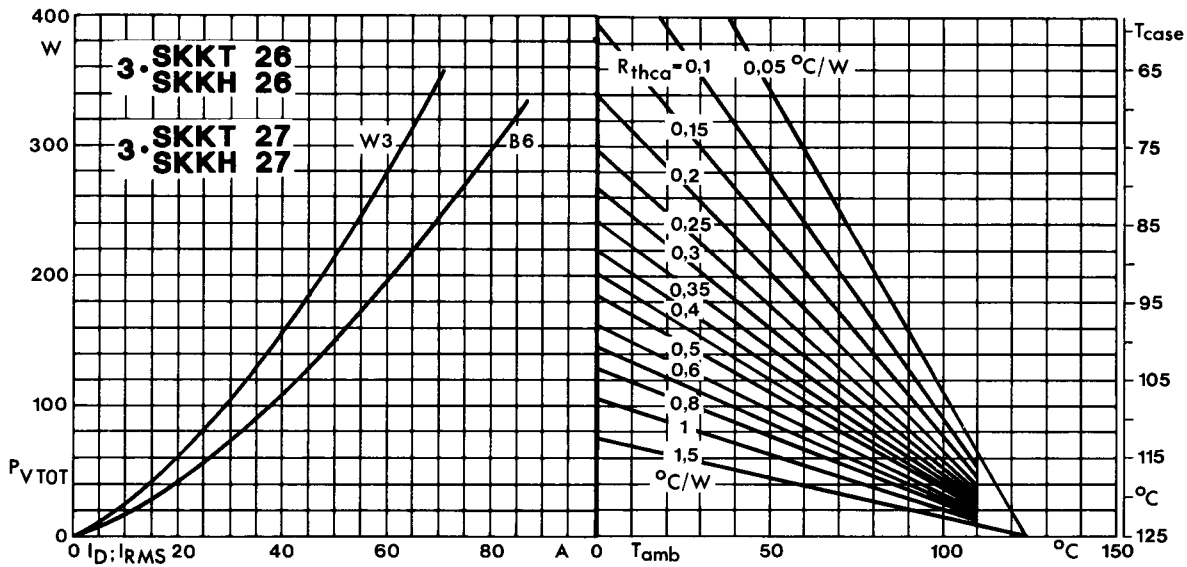


Fig. 4 Power dissipation of three modules vs. direct and rms current and case temperature

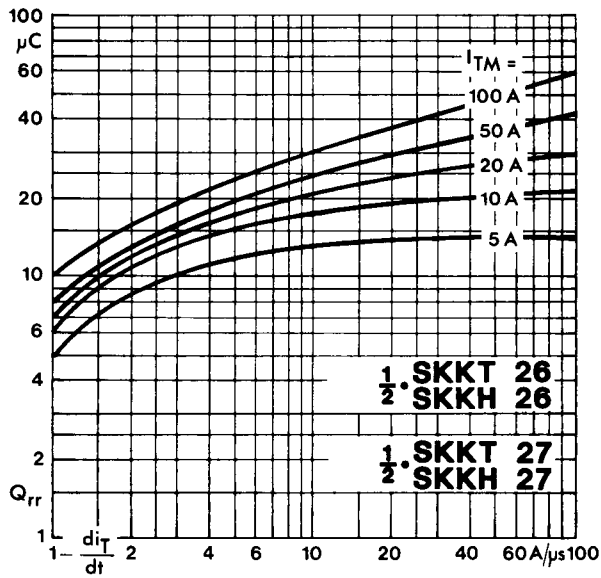


Fig. 5 Recovered charge vs. current decrease

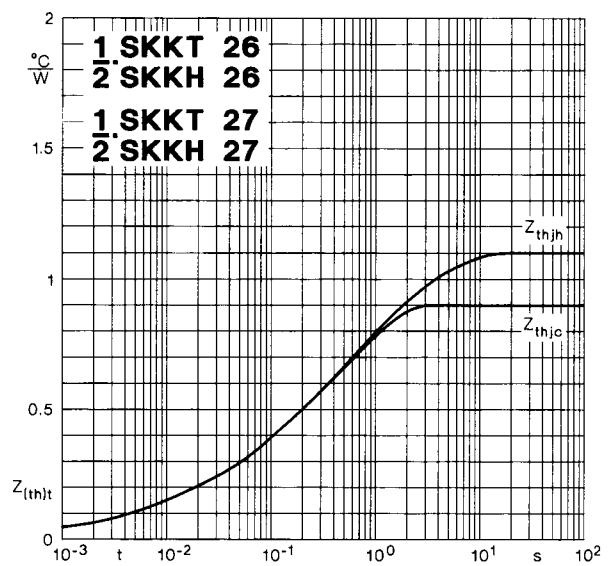


Fig. 6 Transient thermal impedance vs. time

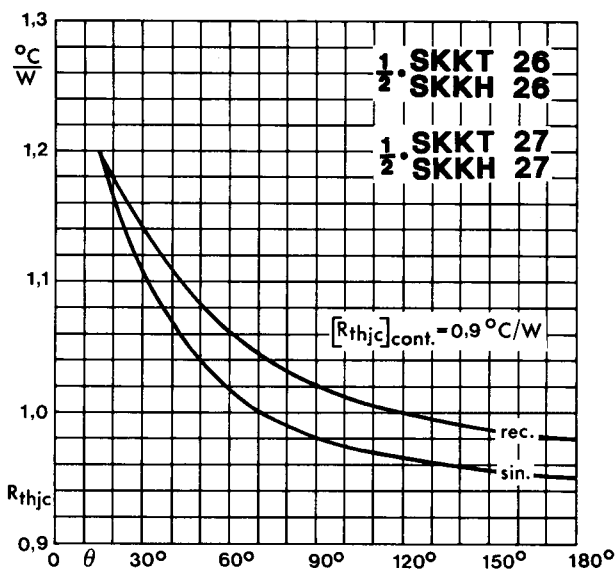


Fig. 7 Thermal resistance vs. conduction angle

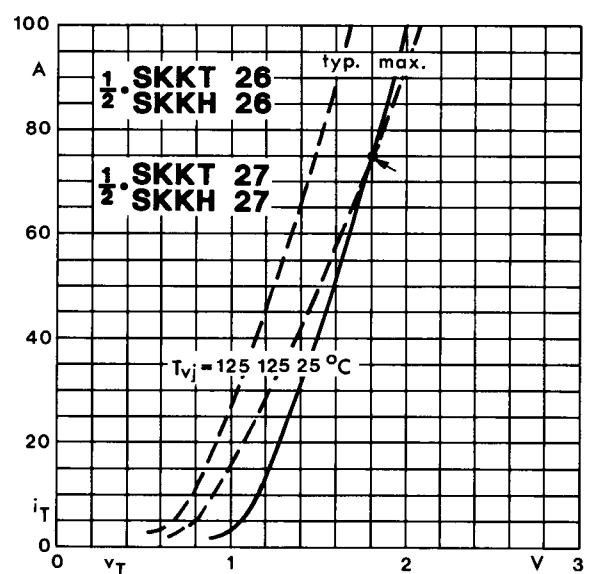


Fig. 8 On-state characteristics

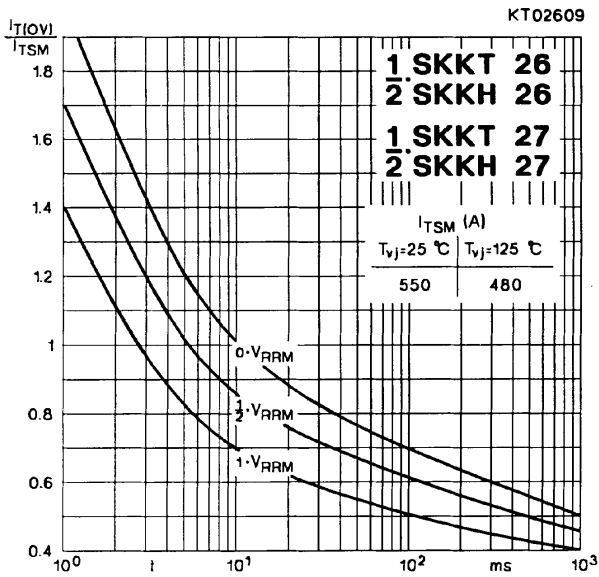


Fig. 9 Surge overload current vs. time

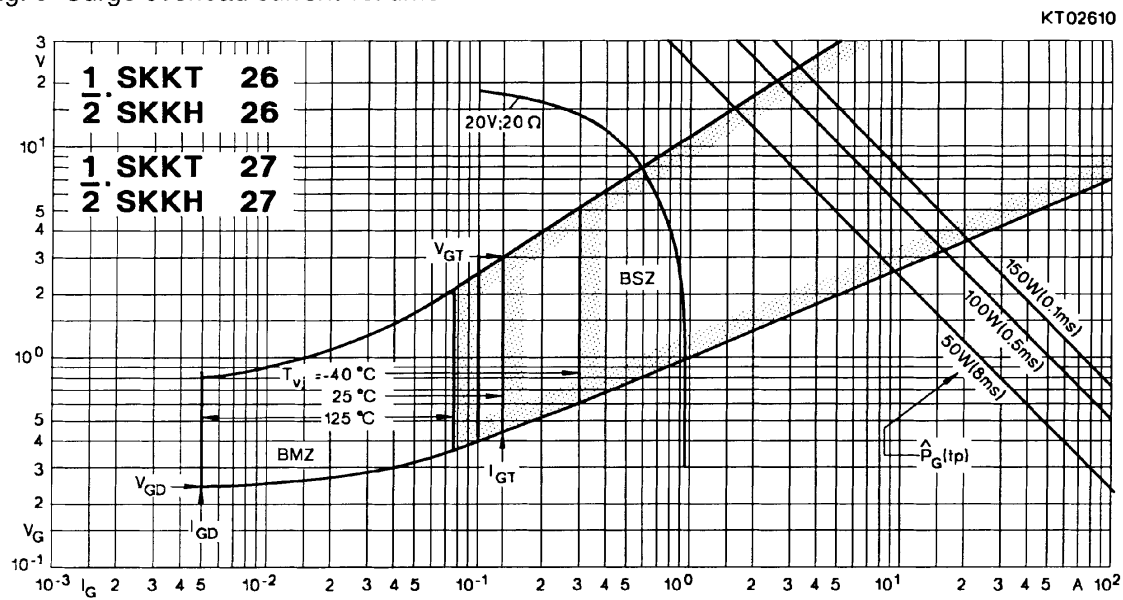
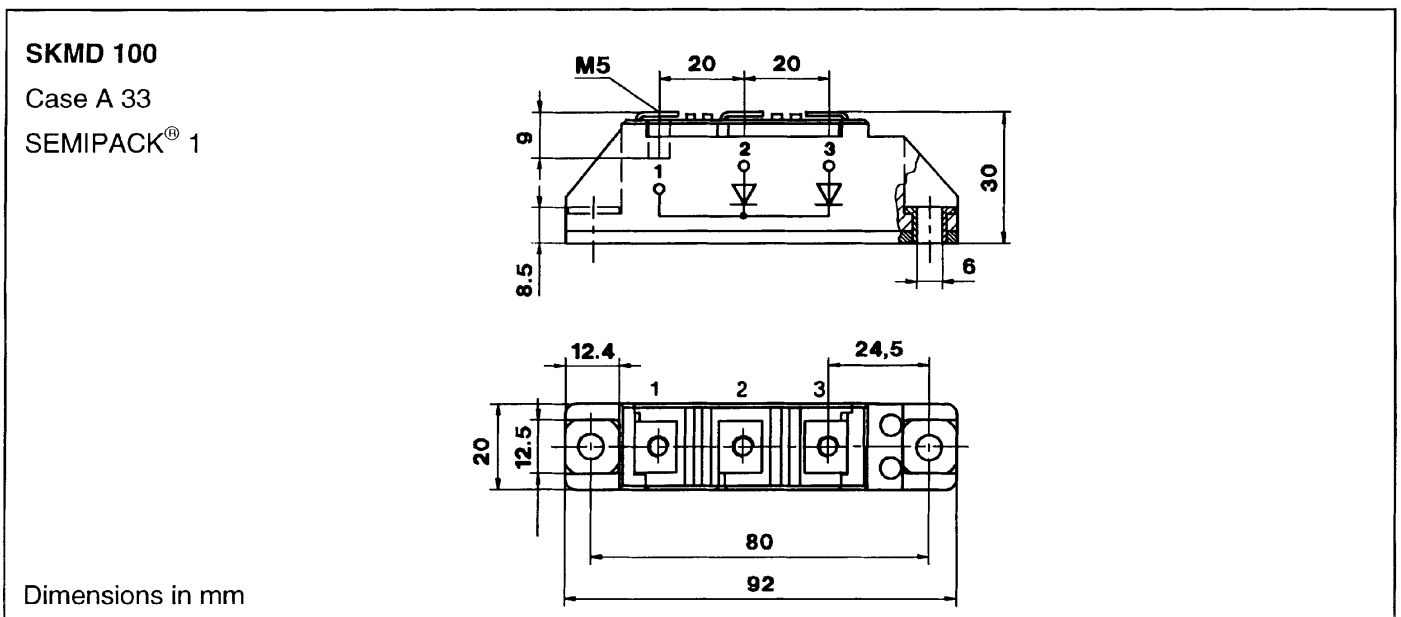


Fig. 10 Gate trigger characteristics



SKKT 19 ... 105

Case A 5

IEC 192-2: A 77 A

JEDEC: TO-240 AA

SEMIPACK® 1

UL recognized, file no. E 63 532



Dimensions in mm

SKKT 20/ ... 106/

Case A 46

IEC 192-2: A 77 A

JEDEC: TO-240 AA

SEMIPACK® 1



Dimensions in mm

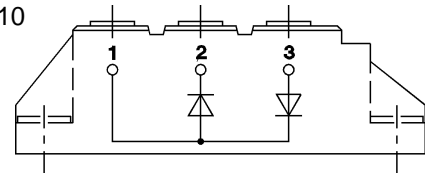
SKKH 26 ... 105

Case A 6



SKKD 26 ... 100

Case A 10



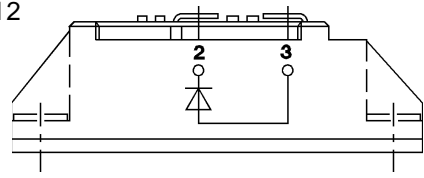
SKNH 56 ... 91

Case A 7



SKKE 81

Case A 12



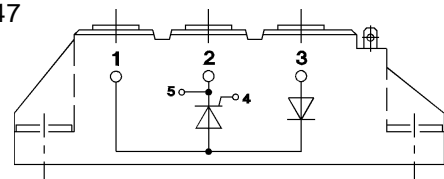
SKKL 56 ... 105

Case A 9



SKKH 27 ... 106

Case A 47



SKND 46 ... 81

Case A 19



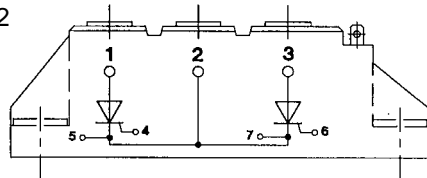
SKKT 20 B ... 106 B

Case A 48



SKMT 92

Case A 72



SKKL 42 ... 106

Case A 59

